

RJ45, MODULAR JACK 8 POSITION, 8 CONTACTS, SHIELD, WITH LEDS

1.0 SCOPE

This Product Specification covers the 1.27 mm (.050 inch) centerline (pitch) printed circuit board (PCB) modular jack connector series with selective gold and tin plating.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

RJ45, MODULAR JACK 8 POSITION, 8 CONTACTS, SHIELD, WITH LEDS P/N: 48146-0001

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate sales drawings (SD-48146-001) for information on dimensions, materials, plating and markings.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

FCC RULES AND REGULATIONS, PART 68, SUBPART F ANSI/EIA/TIA-568 IEC-60603-7 UL 1863 MIL-STD-202 EIA-364

4.0 RATINGS OF CONNECTOR

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1. Rate Voltage: 150 V _{RMS} AC Rate Current: 1.5 A

2. Operating temperature: -40°C to +70°C

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PS-48146-001		JEFF	Allen Lin	Wilson	Chang
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5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

DESCRIPTION	TEST CONDITION	REQUIREMENT
Contact Resistance	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA.	20 milliohms (initial) 40 milliohms (final)
Insulation Resistance	Unmated connector, mounted to a PCB: apply a voltage of 100 VDC between adjacent terminals and between terminals to ground.	500 Megohms MINIMUM
Dielectric Withstanding Voltage	1000 VAC (1mA cutoff current) for 60 seconds duration between adjacent terminals and terminals.	No Breakdown
Current Temperature Rating	Mate connector and measure the temperature rise at the rated current (1.5Amps).	30 ℃ rise maximum from initial

5.2 MECHANICAL REQUIREMENTS

DESCRIPTION	TEST CONDITION	REQUIREMENT
Connector Mate Force	Mate connector at a rate of 25 ± 6 mm (1 ± 1/4 inch) per minute.	35 N (8 lbf) MAXIMUM
Durability	Mate connectors up to 750 cycles at a maximum rate of 10 cycles per minute prior to Environmental Tests.	20 milliohms (initial) 40 milliohms (final)
Vibration (Random)	Amplitude: 1.50mm (.060") peak to peak Sweep: 10-55-10 Hz in one minute Duration: 15 minutes Direction: X, Y,Z axis (45 minutes total)	20 milliohms (initial) 40 milliohms (final)
Plug Retention Fo	Apply an axial pullout force on the plug at a rate of 25 ± 6 mm $(1 \pm \frac{1}{4})$ inch).	89 N (20 lbf) MINIMUM
Shock (Mechanical)	Mate connectors and shock at 50 G Halfsine, 11ms form shocks in the X, Y, Z axis (9 shocks total).	20 milliohms (initial) 40 milliohms (final)
Solderability	Dip solder tails into the molten solder (held at $245 \pm 5^{\circ}$ C) up to 1.0mm from the bottom of the housing fo 5 ± 1 second	Solderable area shall have minimum of 95 % solder coverage

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5.3 ENVIRONMENTAL REQUIREMENTS

DESCRIPTION	TEST CONDITION	REQUIREMENT
Shock (Thermal)	Mate connectors; expose to 10 cycles of: -40°C to +85°C 30 minutes dwell	20 milliohms (initial) 40 milliohms (final) & Visual: No Damage
Thermal Aging	Mate connectors; expose to: 240 hours at 85 ± 2 °C	20 milliohms (initial) 40 milliohms (final) & Visual: No Damage
Humidity (Cycling)	Mate connectors: expose to 10 cycles at 90-95% relative humidity with temperatures at +25°C and +65°C per MIL-STD-202F method 106F (without -10°C dip)	20 milliohms (initial) 40 milliohms (final) & Dielectric Withstanding Voltage: No Breakdown at 500 VAC & Insulation Resistance: 200 Megohms MINIMUM & Visual: No Damage
Solder Resistance	Dip connector terminal tails in solder: Solder Duration: 5±0.5 seconds Solder Temperature: 260±5°C {Recommended same parameters as SMES-152.}	Visual: No Damage to insulator material
Salt Spray	5±1% salt solution Duration 48 hrs	20 milliohms (initial) 40 milliohms (final) & Visual: No Damage

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5.5 Test Group

	Test Group					
Test Item	Α		В	С	D	Individual
Examination of Product	1,5		1,8	1,5	1,6	
Contact Resistance	4			2,4	2,5	
Insulation Resistance			2,6			
Dielectric Withstanding Voltage			3,7			
Current Temperature Rating						*
Connector Mate Force	2					
Durability	3					
Vibration (Random)					3	
Shock (Mechanical)					4	
Solderability						*
Shock (Thermal)			4			
Thermal Aging				3		
Humidity (Cycling)		1	5			
Solder Resistance						*
Salt Spray						*
Plug Retention Force						*
Sample Size	5		5	5	5	5

6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. See appropriate sales drawings.

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7.0 OTHER INFORMATION

7.1 LED ELECTRICAL PERFORMANCE

PARAMETER	GREEN		UNITS	TEST CONDITION		
Power Dissipation	105		105		mW	N/A
Reverse Voltage	5		V	N/A		
Peak Wavelength	565		nM	IF=20mA		
Forward Voltage	2.2	MAX. = 2.5	V	IF=20mA		

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